

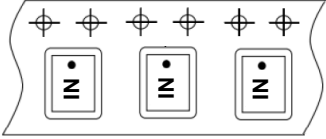
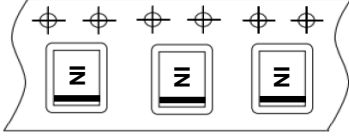

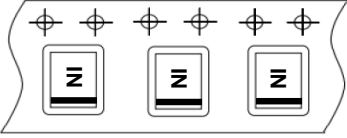


## Marking Information

<p><b>DMN2300UFB-7</b></p>	<div style="display: flex; justify-content: space-around; align-items: flex-start;"> <div style="text-align: center;">  <p>Top View Dot Denotes Drain Side</p> </div> <div style="text-align: center;"> <p>From date code 1527 (YYWW), this changes to:</p>  <p>Top View Bar Denotes Gate and Source Side</p> </div> </div> <div style="display: flex; justify-content: space-around; align-items: center; margin-top: 20px;">   </div>
<p><b>DMN2300UFB-7B</b></p>	<div style="text-align: center; margin-bottom: 20px;">  <p>Top View Bar Denotes Gate and Source Side</p> </div> <div style="display: flex; justify-content: space-between; align-items: center;">  <div> <p>NI = Part Marking Code</p> </div> </div>

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Continuous Drain Current V <sub>GS</sub> = 4.5V	Steady State	T <sub>A</sub> = +25°C (Note 5)	I <sub>D</sub>	1.32	A
		T <sub>A</sub> = +85°C (Note 5)		0.94	
		T <sub>A</sub> = +25°C (Note 6)		1.78	
Pulsed Drain Current (Note 7)			I <sub>DM</sub>	8	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	0.468	W
Power Dissipation (Note 6)	P <sub>D</sub>	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	267	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>θJA</sub>	104	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 8)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 10μA
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	—	—	1	μA	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	10	μA	V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 8)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.45	—	0.95	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	—	175	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 300mA
		—	—	240		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 250mA
		—	—	360		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 100mA
		—	—	—		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 100mA
Forward Transfer Admittance	Y <sub>fs</sub>	40	—	—	mS	V <sub>DS</sub> = 3V, I <sub>D</sub> = 30mA
Diode Forward Voltage	V <sub>SD</sub>	—	0.7	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 300mA
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>iss</sub>	—	67.6	—	pF	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	9.74	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	7.58	—	pF	
Gate Resistance	R <sub>g</sub>	—	68.51	—	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge	Q <sub>g</sub>	—	0.89	—	nC	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 1A
Gate-Source Charge	Q <sub>gs</sub>	—	0.14	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	0.16	—	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	—	4.92	—	ns	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1A V <sub>GS</sub> = 4.5V, R <sub>G</sub> = 6Ω
Turn-On Rise Time	t <sub>R</sub>	—	6.93	—	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	21.71	—	ns	
Turn-Off Fall Time	t <sub>F</sub>	—	10.62	—	ns	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
  - Device mounted on FR-4 substrate PC board, 2oz copper, with 25mm X 25mm square copper plate.
  - Device mounted on minimum recommended pad layout test board, 10μs pulse duty cycle = 1%.
  - Short duration pulse test used to minimize self-heating effect.

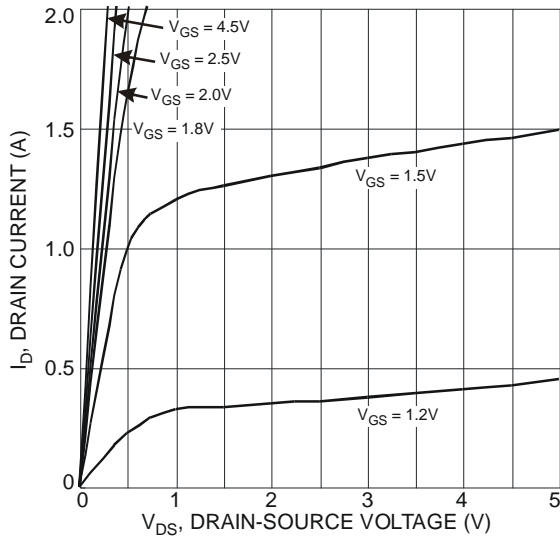


Fig. 1 Typical Output Characteristic

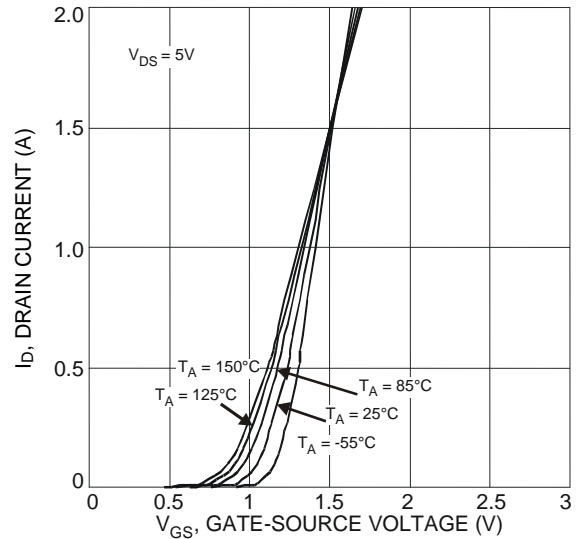


Fig. 2 Typical Transfer Characteristic

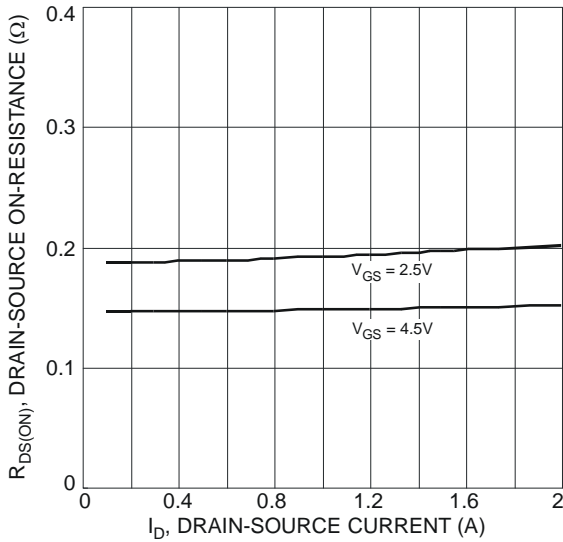


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

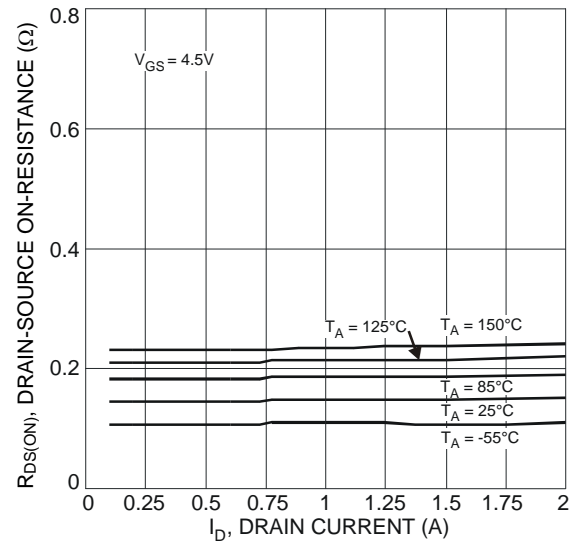


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

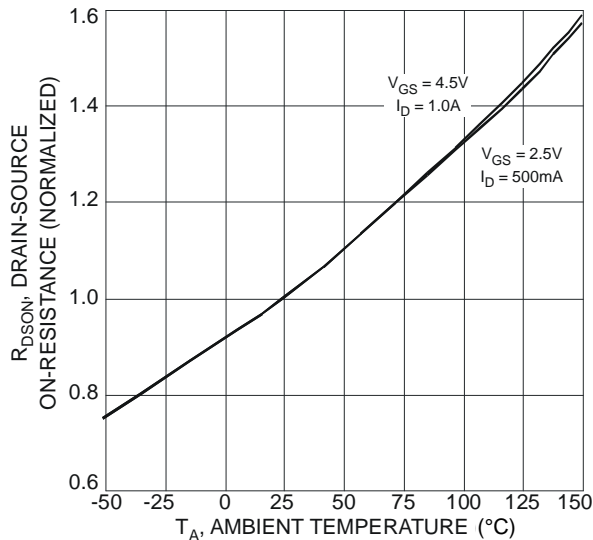


Fig. 5 On-Resistance Variation with Temperature

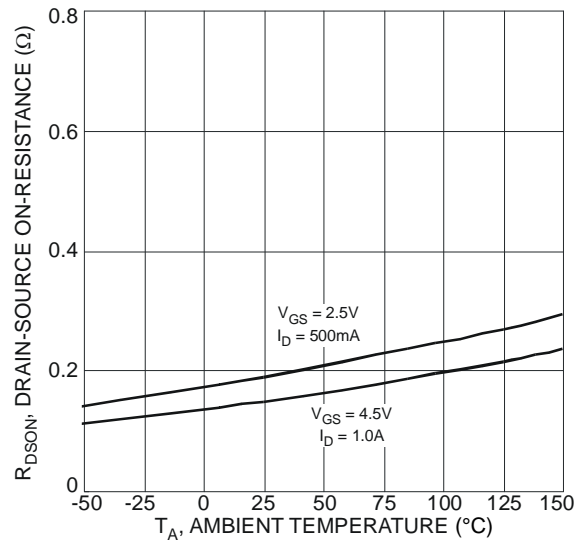


Fig. 6 On-Resistance Variation with Temperature

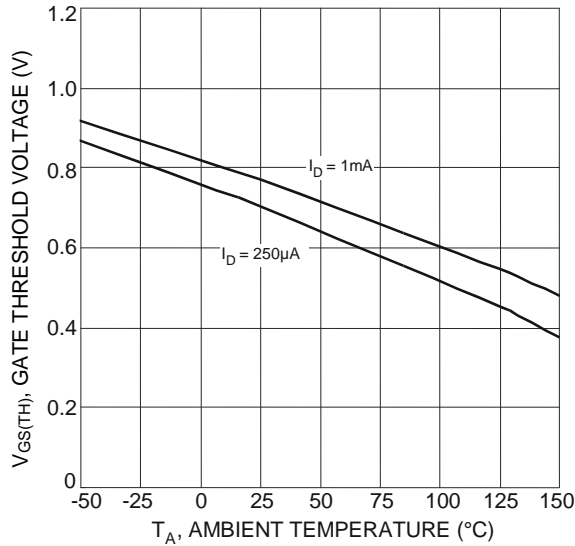


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

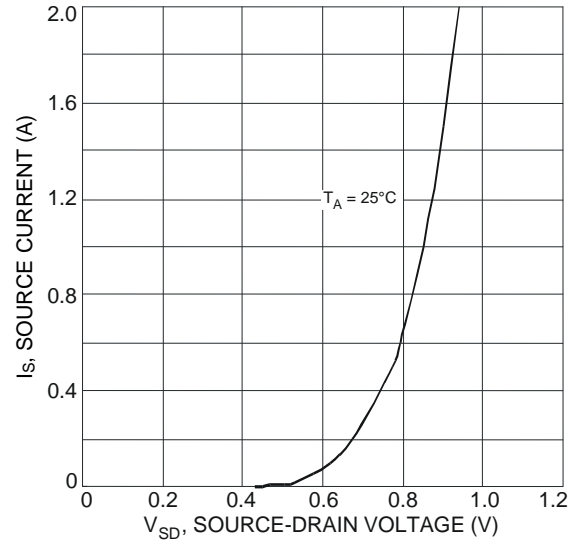


Fig. 8 Diode Forward Voltage vs. Current

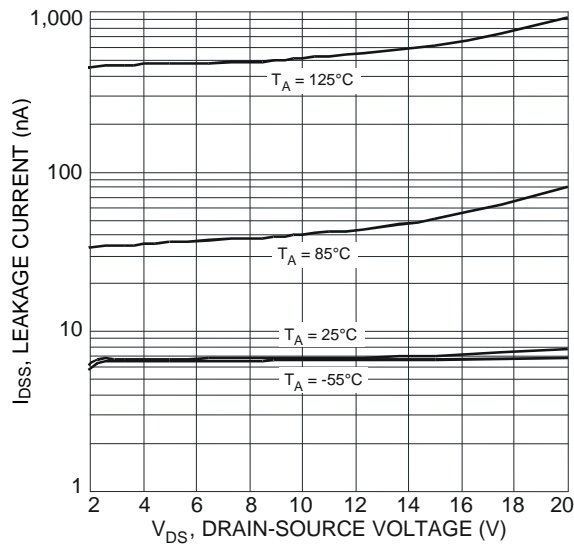


Fig. 9 Typical Leakage Current vs. Drain-Source Voltage

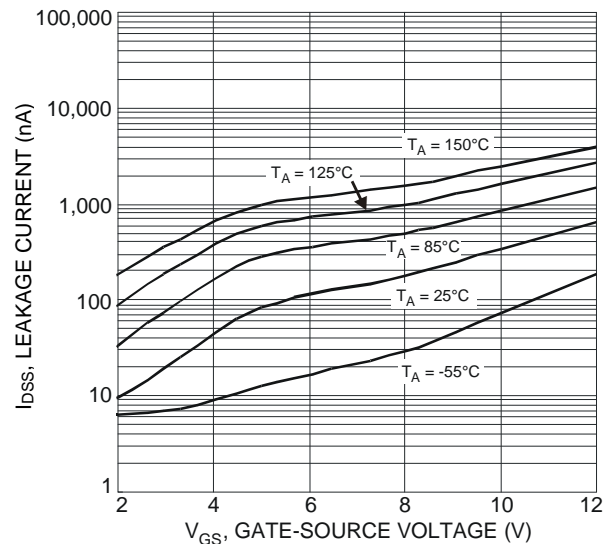


Fig.10 Leakage Current vs. Gate-Source Voltage

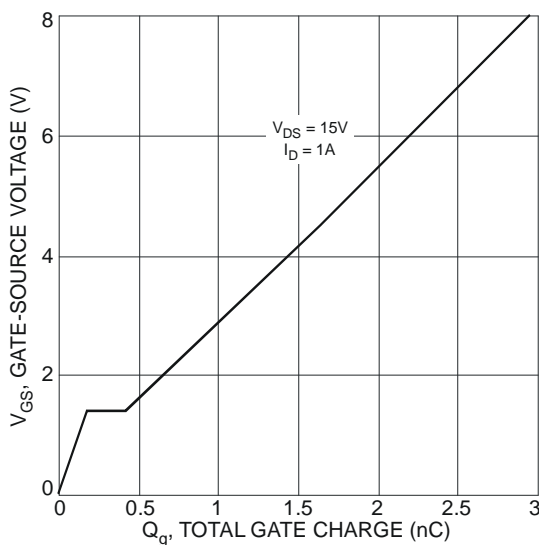


Fig. 11 Gate-Charge Characteristics

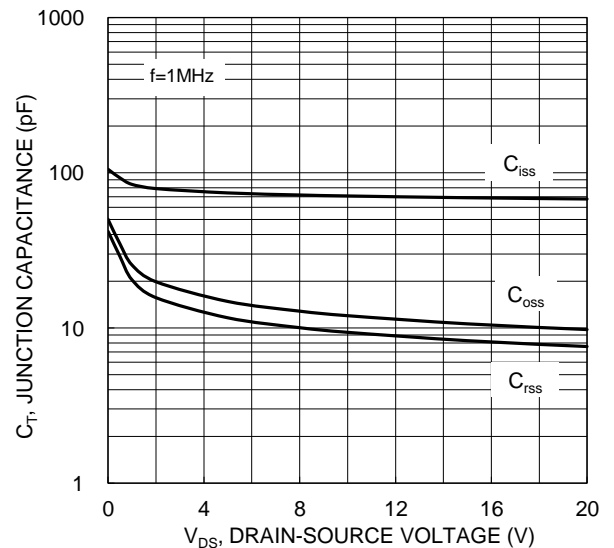


Fig. 12 Typical Junction Capacitance

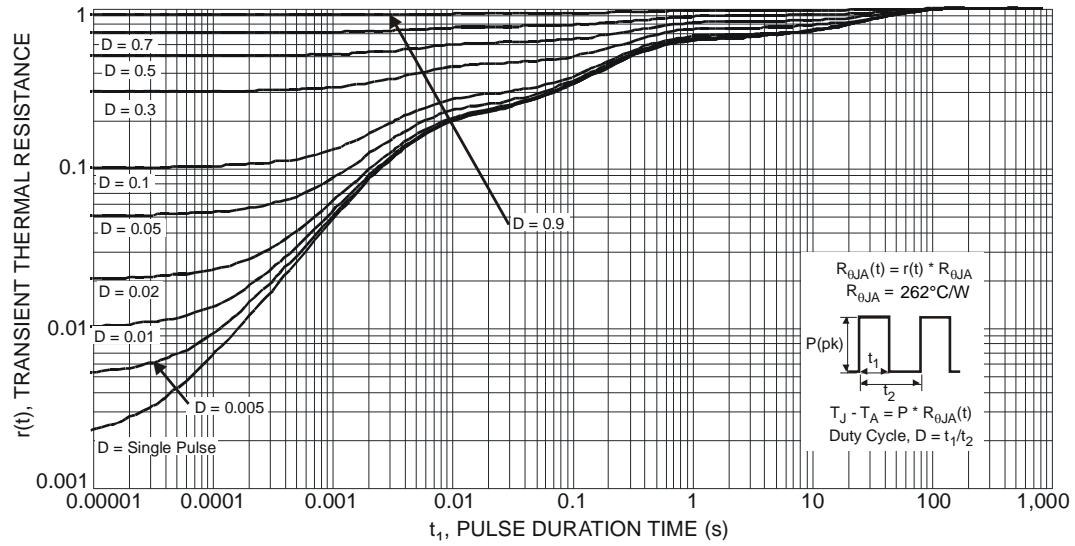
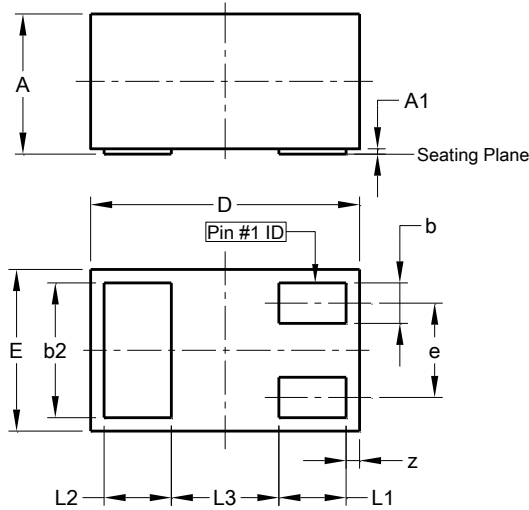


Fig. 13 Transient Thermal Resistance

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### X1-DFN1006-3

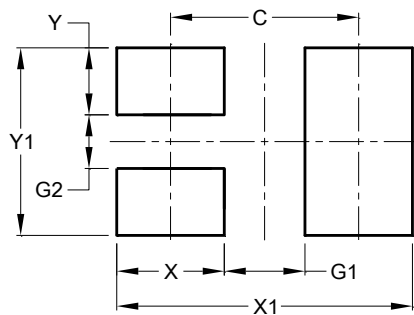


X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0.00	0.05	0.03
b	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	-	-	0.40
z	0.02	0.08	0.05
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### X1-DFN1006-3



Dimensions	Value (in mm)
C	0.70
G1	0.30
G2	0.20
X	0.40
X1	1.10
Y	0.25
Y1	0.70

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